


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U031K8U6	70MG*459XXXA	A	998Z	22-09-2023
Amount	UoM	Unit type	ST ECOPACK Grade	
49.32	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	70MG*459XXXX				6000001.0	1000005.1				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.120	mg	supplier	die	Silicon (Si)	7440-21-3		1.915	mg	903302	38826				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	4717	203				
				supplier	metallization	Copper (Cu)	7440-50-8		0.087	mg	41038	1764				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.028	mg	13208	568				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	472	20				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	472	20				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	10377	446				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.056	mg	26415	1135				
				Glue Epoxy (EN4900GC)	M-011 Other inorganic materials	0.308	mg	Supplier	Organic Compounds	Acrylic resin	Proprietary		0.022	mg	70000	438
								Supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.006	mg	20000	125
Supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.005	mg	15000	94				
Supplier	Organic Compounds	Acrylate	Proprietary						0.017	mg	54000	338				
Supplier	Organic Compounds	Epoxy resin	Proprietary						0.009	mg	30000	188				
Supplier	Organic Compounds	Peroxide	Proprietary						0.002	mg	8000	50				
Supplier	Organic Compounds	Additive	Proprietary						0.006	mg	18000	113				
Supplier	Metals	Silver (Ag)	7440-22-4						0.242	mg	785000	4909				
Encapsulation (EME-G770)	M-011 Other inorganic materials	16.646	mg					Supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.350	mg	21000	7087
								Supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.350	mg	21000	7087
				Supplier	Organic Compounds	Phenol Resin A	Proprietary		0.350	mg	21000	7087				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		12.991	mg	780450	263396				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		1.920	mg	115320	38920				
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.104	mg	6230	2103				
				Supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.233	mg	14000	4725				
				Supplier	Organic Compounds	Phenol Resin B	Proprietary		0.350	mg	21000	7087				
				Bonding wire (Au)	Bonding Wire	0.329	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.329	mg	1000000	6676
				Plating (Sn)	M-011 Other inorganic materials	0.719	mg	Supplier	Metals	Tin (Sn)	7440-31-5		0.719	mg	1000000	14576
Leadframe (C7025 + Ag)	Copper & its alloys	29.200	mg	Supplier	Metals	Copper (Cu)	7440-50-8		26.780	mg	917140	542970				
				Supplier	Metals	Nickel (Ni)	7440-02-0		0.657	mg	22500	13321				
				Supplier	Metals	Silicon (Si)	7440-21-3		0.076	mg	2600	1539				
				Supplier	Metals	Magnesium (Mg)	7439-95-4		0.034	mg	1150	681				
				Supplier	Metals	Silver (Ag)	7440-22-4		1.653	mg	56610	33515				